

Date: September 2017
Rev: VII
No. of Components: Two
Mix Ratio by Weight: 10 : 1
Specific Gravity: Part A: 2.45 Part B: 2.14
Pot Life: 15 Hours
Shelf Life- Bulk: One year at room temperature

Recommended Cure: 150°C / 1 Hour

Minimum Alternative Cure(s):
May not achieve performance properties listed below
 150°C / 5 Minutes
 120°C / 15 Minutes
 80°C / 90 Minutes

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

Product Description: EPO-TEK® H21D is a two component, high Tg, silver-filled epoxy designed for chip bonding in microelectronic and optoelectronic applications.

Typical Properties: Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results.
 Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:			
* Color (before cure):	Part A: Silver	Part B: Silver	
* Consistency:	Smooth paste		
* Viscosity (23°C) @ 20 rpm:	14,000-20,400	cPs	
Thixotropic Index:	2.6		
* Glass Transition Temp:	≥ 100 °C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)		
Coefficient of Thermal Expansion (CTE):			
Below Tg:	42	x 10 ⁻⁶ in/in°C	
Above Tg:	225	x 10 ⁻⁶ in/in°C	
Shore D Hardness:	60		
Lap Shear @ 23°C:	1,504	psi	
Die Shear @ 23°C:	≥ 10	Kg	3,556 psi
Degradation Temp:	416 °C		
Weight Loss:			
@ 200°C:	0.03	%	
@ 250°C:	0.06	%	
@ 300°C:	0.17	%	
Suggested Operating Temperature:	< 350 °C (Intermittent)		
Storage Modulus:	802,491	psi	
Ion Content:	Cl:	64 ppm	Na ⁺ : 72 ppm
	NH ₄ ⁺ :	121 ppm	K ⁺ : ND ppm
* Particle Size:	≤ 45 microns		

ELECTRICAL AND THERMAL PROPERTIES:		
Thermal Conductivity:	1.0	W/mK
* Volume Resistivity @ 23°C:	≤ 0.0009	Ohm-cm

Epoxyes and Adhesives for Demanding Applications™

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

EPOXY TECHNOLOGY, INC.

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EPO-TEK® H21D Advantages & Suggested Application Notes:

- Extended pot-life and can be cured at relatively low temperatures such as 80°C.
- Designed to be used in the 300°C range for applications such as wire bonding operations and eutectic lid-sealing processes.
- Contains no solvents or thinners. NASA approved, low outgassing epoxy – <http://outgassing.nasa.gov/>
- Also suggested for hybrid - aerospace circuits found in RF / Microwave devices like cockpits and satellites.
- Paste-like rheology allows for application by commercial dispensing equipment, stamping, screen printing, or by hand with spatula or toothpick.
- Compatible with Au-plated ceramic substrates found in traditional and custom hybrids.

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